

(54) SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE  
(11) 4-56262 (A) (43) 24.2.1992 (19) JP  
(21) Appl. No. 2-167207 (22) 25.6.1990  
(71) MATSUSHITA ELECTRON CORP. (72) SUSUMU SANAI  
(51) Int. Cl.<sup>7</sup> H01L25/065; H01L25/07; H01L25/18; H01L27/00

**PURPOSE:** To enable a semiconductor integrated circuit device to be miniaturized and improved in electrical properties by a method wherein two or more semiconductor chips are stacked up on a board.

**CONSTITUTION:** Semiconductor chips 1, 2, and 3 are stacked up on a thin Au film 10 on a board 4 and bonded, and the chips 1, 2, and 3 are connected to a wiring 6 provided onto the board 4 with bonding wires, and the chips are coated hard with resin 7 except a bonding part on the board. Then, the chip 2 is bonded with an adhesive agent 8; the chip 2 is connected to the wiring 6 provided onto the board 4 through bonding, and a process the same as above is repeated, whereby the chip 3 is connected to the wiring 6 on the board 4. Lastly, the whole body is covered with a resin 9.

